

RF AMPLIFIER

MODEL *TM3090*

Available as: TM3090, 4 Pin TO-8 (T4)
 TN3090, 4 Pin Surface Mount (SM3)
 FP3090, 4 Pin Flatpack (FP4)
 BX3090, Connectorized Housing (H1)

Features

- Low Noise Figure: 1.75 dB Typical
- Output Power: +19 dBm Typical
- Operating Temp. - 55 °C to +85 °C
- Environmental Screening Available

Specifications

CHARACTERISTIC	TYPICAL Ta= 25 °C	MIN/MAX Ta = -55 °C to +85 °C
Frequency	15 - 200 MHz	15 - 200 MHz
Gain (dB)	14	13 Min.
Power @ 1 dB Comp. (dBm)	+19	+18 Min.
Reverse Isolation (dB)	-20	-17 Max.
VSWR In	1.5:1	2.0:1 Max.
Out	1.5:1	2.0:1 Max.
Noise Figure (dB)	1.75	3.0 Max.
Power Vdc	+10	+10
mA	55	60 Max.

Note: Care should always be taken to effectively ground the case of each unit.

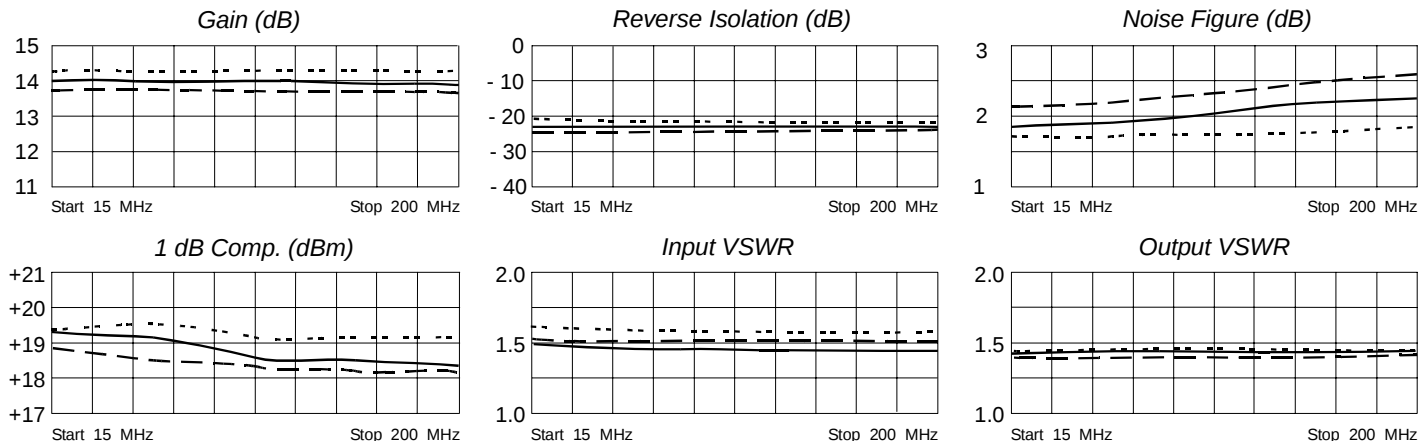
Typical Intermodulation Performance at 25 °C

Second Order Harmonic Intercept Point +53 dBm (Typ.)
 Second Order Two Tone Intercept Point +47 dBm (Typ.)
 Third Order Two Tone Intercept Point +35 dBm (Typ.)

Maximum Ratings

Ambient Operating Temperature -55°C to + 100 °C
 Storage Temperature -62°C to + 125 °C
 Case Temperature + 125 °C
 DC Voltage + 13 Volts
 Continuous RF Input Power + 13 dBm
 Short Term RF Input Power 50 Milliwatts (1 Minute Max.)
 Maximum Peak Power 0.5 Watt (3 µsec Max.)

Typical Performance Data



Legend ——— + 25 °C - - - + 85 °C -55 °C